

In the Specification

Please replace the paragraph starting on page 8, line 24, to page 9, line 8, of the original specification with:

CA

The conductive strips 44 and 46 can be formed by initially masking off all surfaces of the package housing, except the edge of the third shelf 22 with a plating resist maskant 50, as shown in Figure 5. The masked housing can then be dipped into a plating bath 52 as shown in Figure 6. The plating bath 52 plates a conductive material such as copper onto the edge 43 of the first bond shelf 18. The maskant 50 is then removed and the notches 48 can be drilled into the edges of the first bond shelf 18 to separate the plated material into the first and second conductive strips 44 and 46. All exposed copper surfaces may then be plated with gold.

In the Claims

A clean version of the entire set of pending claims is presented on the following page. Only claim 13 has been amended to correct a grammatical error.

Clean Version of the Entire Set of Pending Claim

1 1-12. (Cancelled)

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2 13. (Amended) A method for assembling an electronic package,

3 comprising:

4 forming a housing which has a bond pad located on a bond shelf